



imec

Assessing the environmental impact of integrated circuit chip manufacturing

Cédric Rolin

Program Manager, Sustainable Semiconductor Technologies & Systems

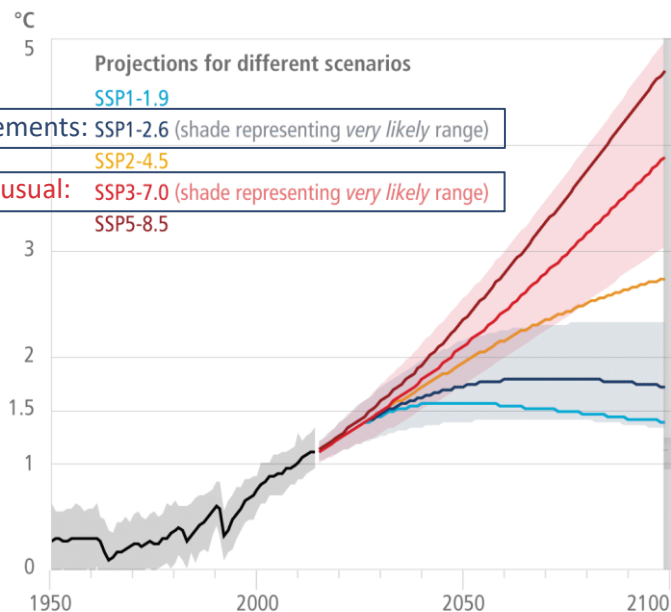
ICOS Workshop, April 26, 2023, 15:00

Session 3: Sustainable Electronics

cedric.rolin@imec.be

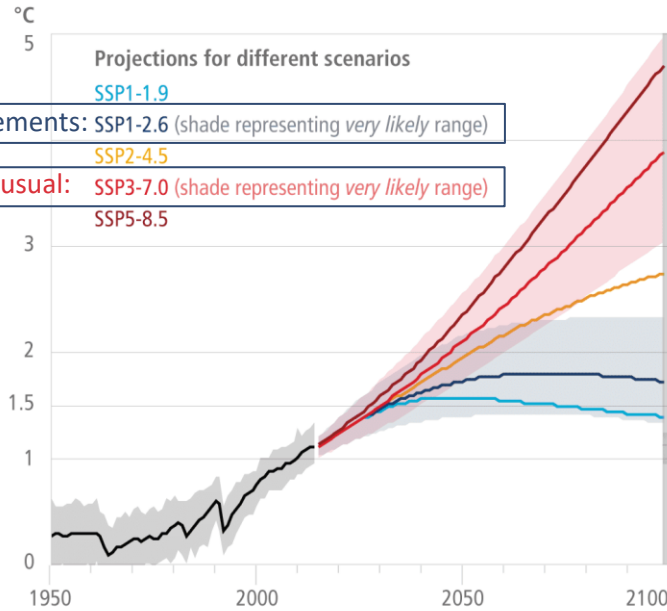
Risks for increasing levels of global warming

Global surface temperature change

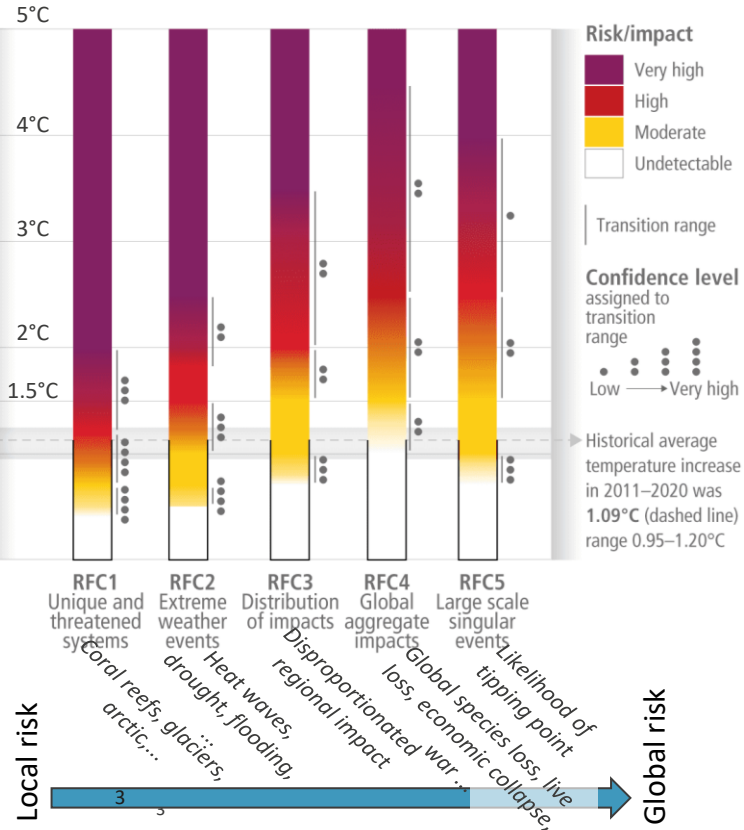


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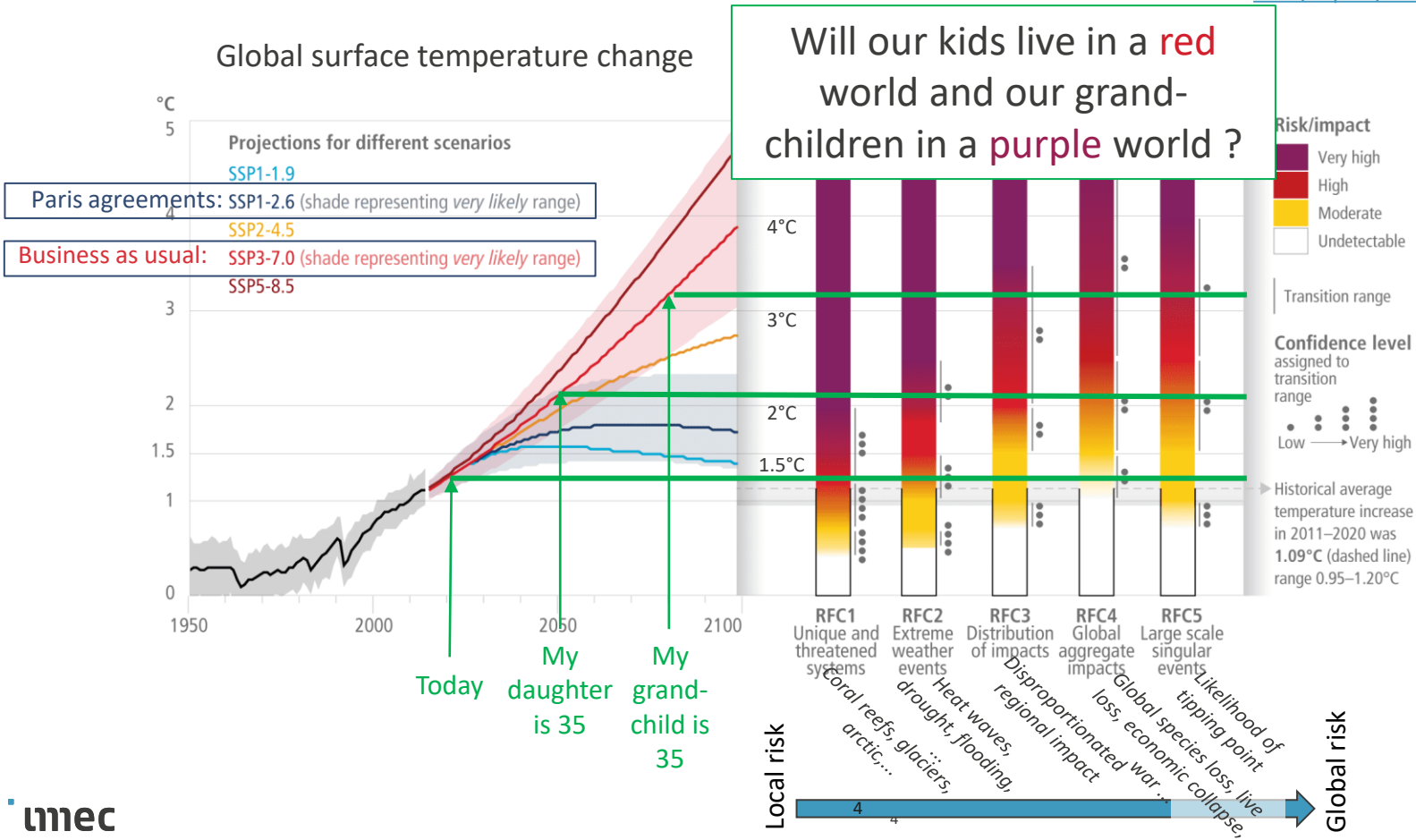


Reasons for concern (RFC)



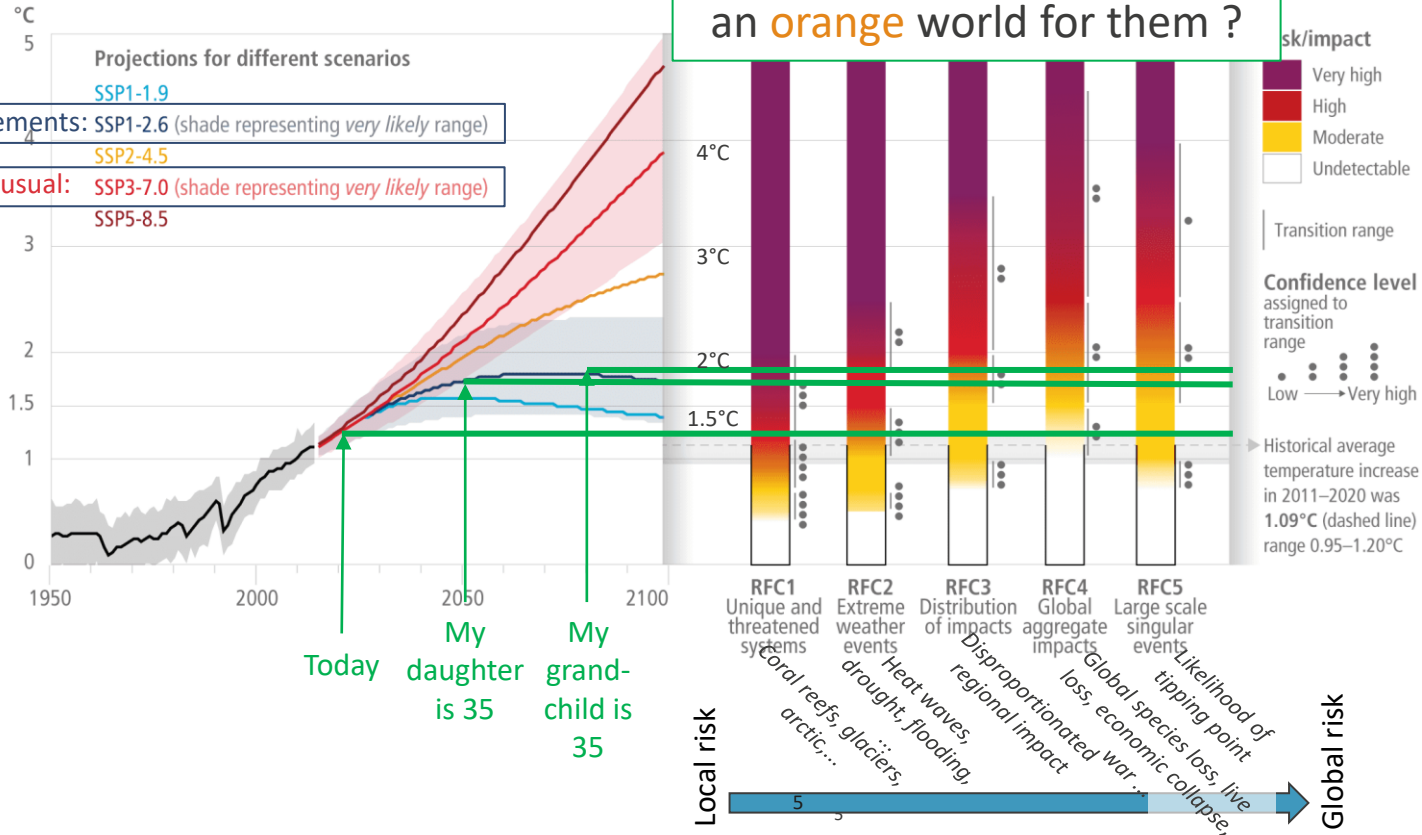
Risks for increasing levels of global warming

IPCC AR6 Synthesis report: Summary for Policy Makers **Figure 4**, March 2023, https://www.ipcc.ch/report/ar6/syr/downloads/report/IPCC_AR6_SYR_SPM.pdf

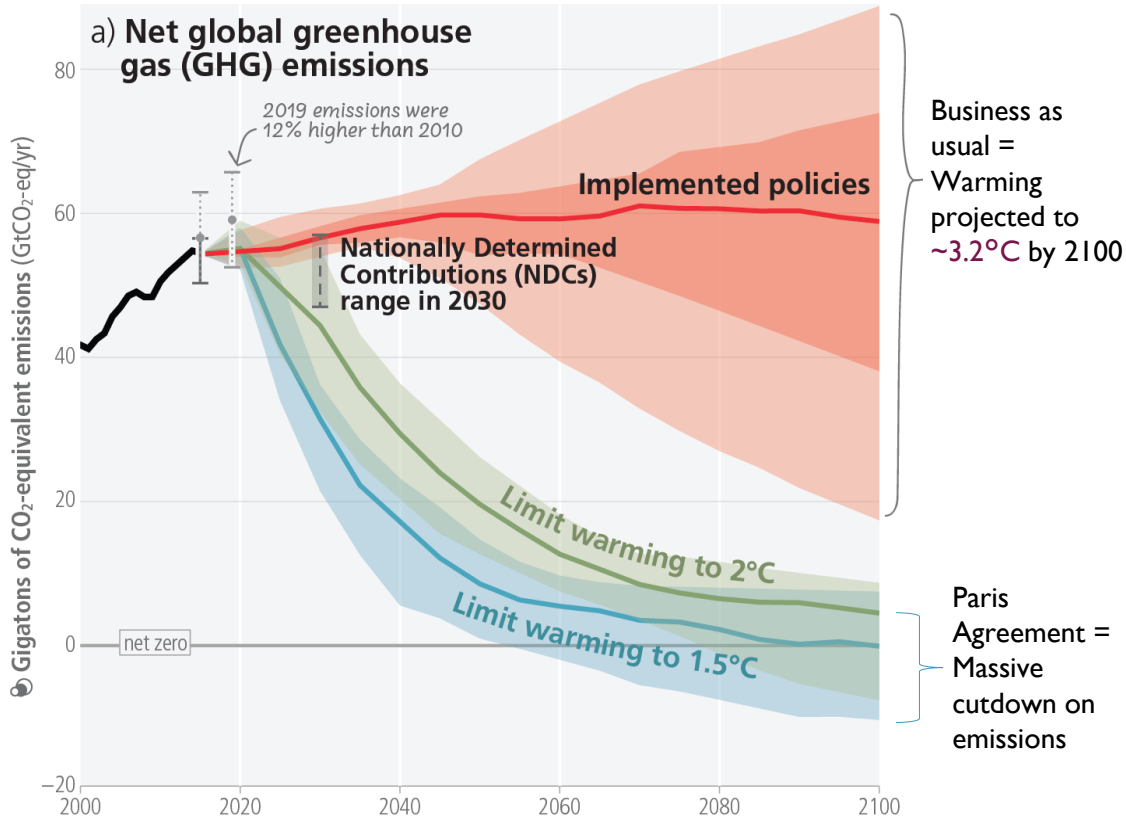


Risks for increasing levels of global warming

Global surface temperature change



Carbon emission projections in IPCC AR6 Synthesis



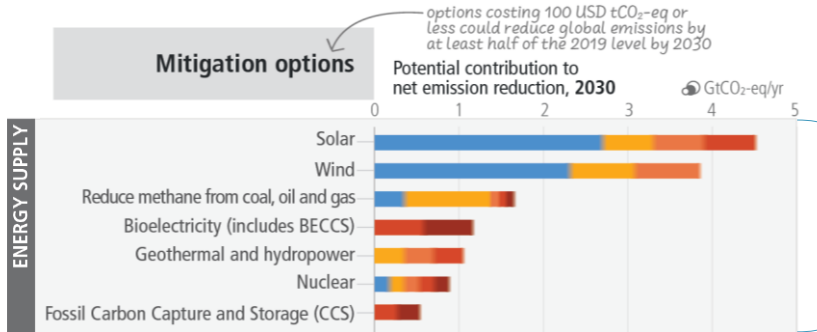
We are on the road to a purple world...

We need to do much better, not only for future generations, but even for ourselves...

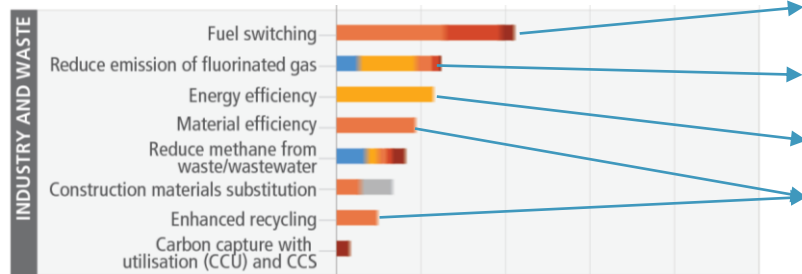
Risk for industry is very high. Semiconductor industry to align on the global efforts.

Opportunities for scaling on climate action in semicon industry

IPCC AR6 Synthesis report: Summary for Policy Makers **Figure 7**, March 2023, https://www.ipcc.ch/report/ar6/syr/downloads/report/IPCC_AR6_SYR_SPM.pdf



More renewable electricity !!!



Reduce natural gas consumption

Replace / Reduce / Abate F-Gasses

Energy efficiency & Industry 4.0

Material circularity

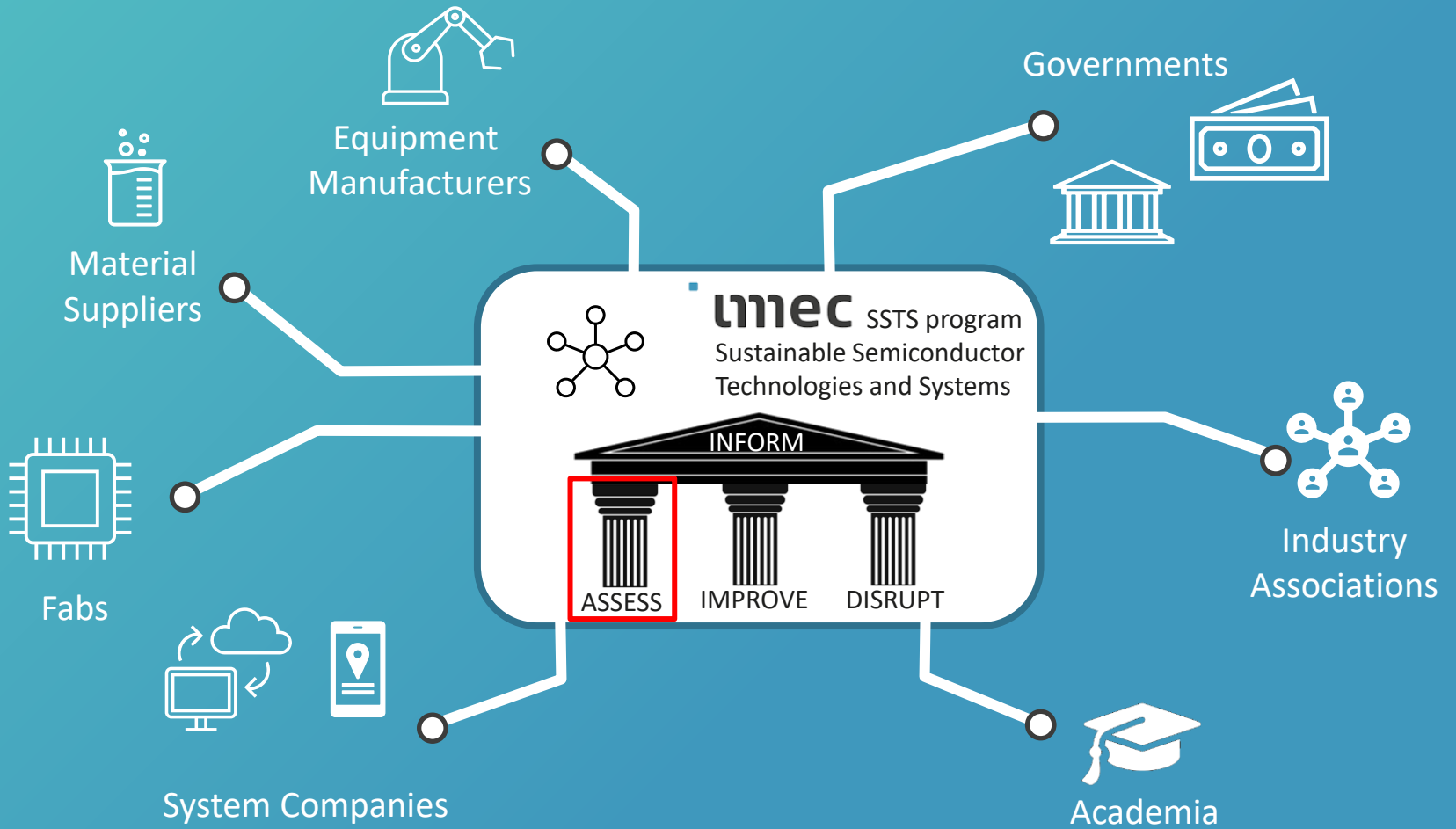
Main levers for change

Net lifetime cost of options:



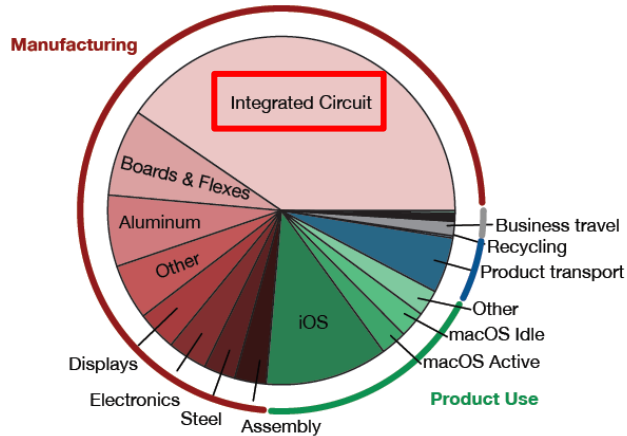
Changes take time.

Need to accelerate on R&D of more sustainable solutions and their implementation in Fabs.

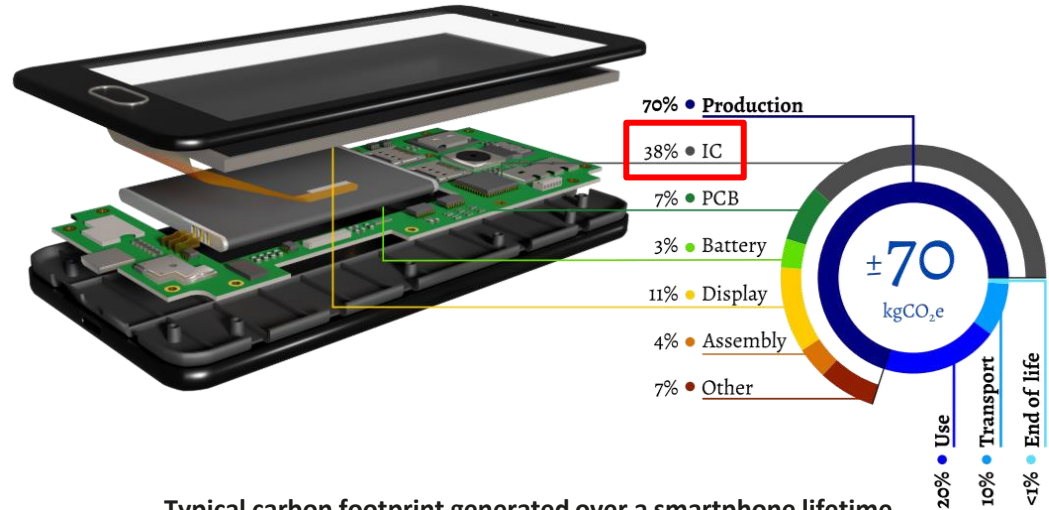


Our mission: Help the semiconductor industry achieve its targets in carbon footprint reduction

The climate impact of Consumer Electronics manufacturing



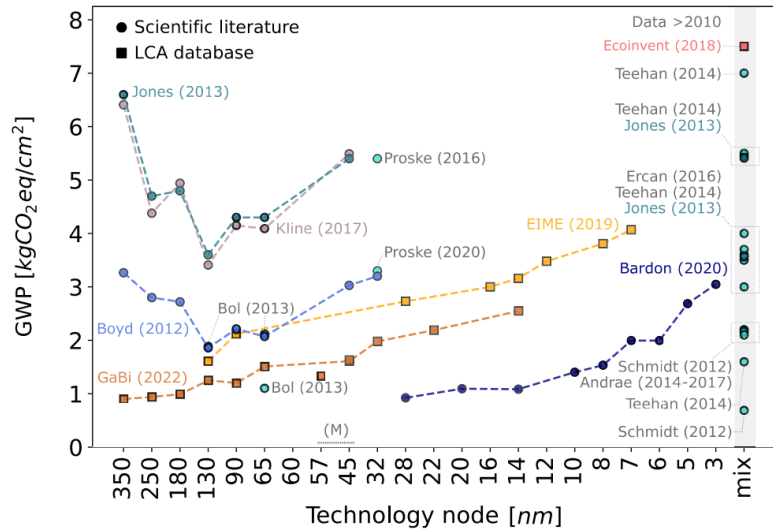
Apple's Carbon-Emission Breakdown
 Source: Gupta et al., 2021 –*The elusive environmental footprint of computing*



Typical carbon footprint generated over a smartphone lifetime
 Source: Moreau et al., 2021 –*Could Unsustainable Electronics Support Sustainability?*

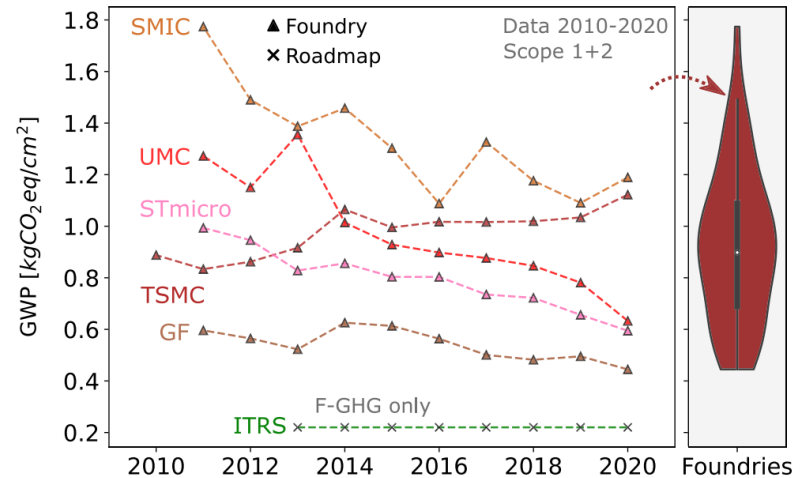
IC chip manufacturing accounts for the largest share of the climate impact, dominating over product use phase

Scattered data over IC chip manufacturing environmental impact



Literature and LCA database data:

- Variable Scope
- Variable sources (Primary vs. Secondary)
- Variable approaches (e.g. Bottom-up vs Top-down)
- Data gaps require “creative” plugging methods



Industry data from public CSR reports:

- Top-down, primary sourced data
- Aggregated over entire company operation, not “per chip” or “per-node”
- Limited scope
- Non-transparent methodology

Source: Pirson et al., 2023 – The Environmental Footprint of IC Production: Review, Analysis, and Lessons From Historical Trends

GWP: Global Warming Potential

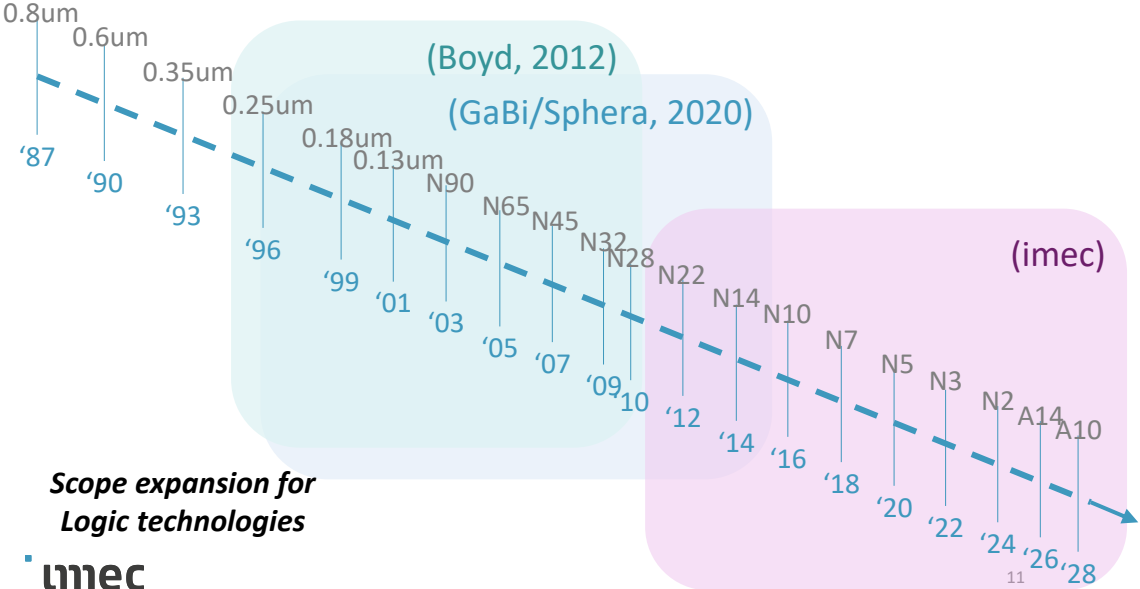
Imec ambition for the SSTS Assess pillar

Close the data gap by providing **quality, transparent data** on environmental impact of IC chip fabrication in a **generic high volume manufacturing plant**

imec.netzero
 a *Virtual Fab* model for environmental impact assessment

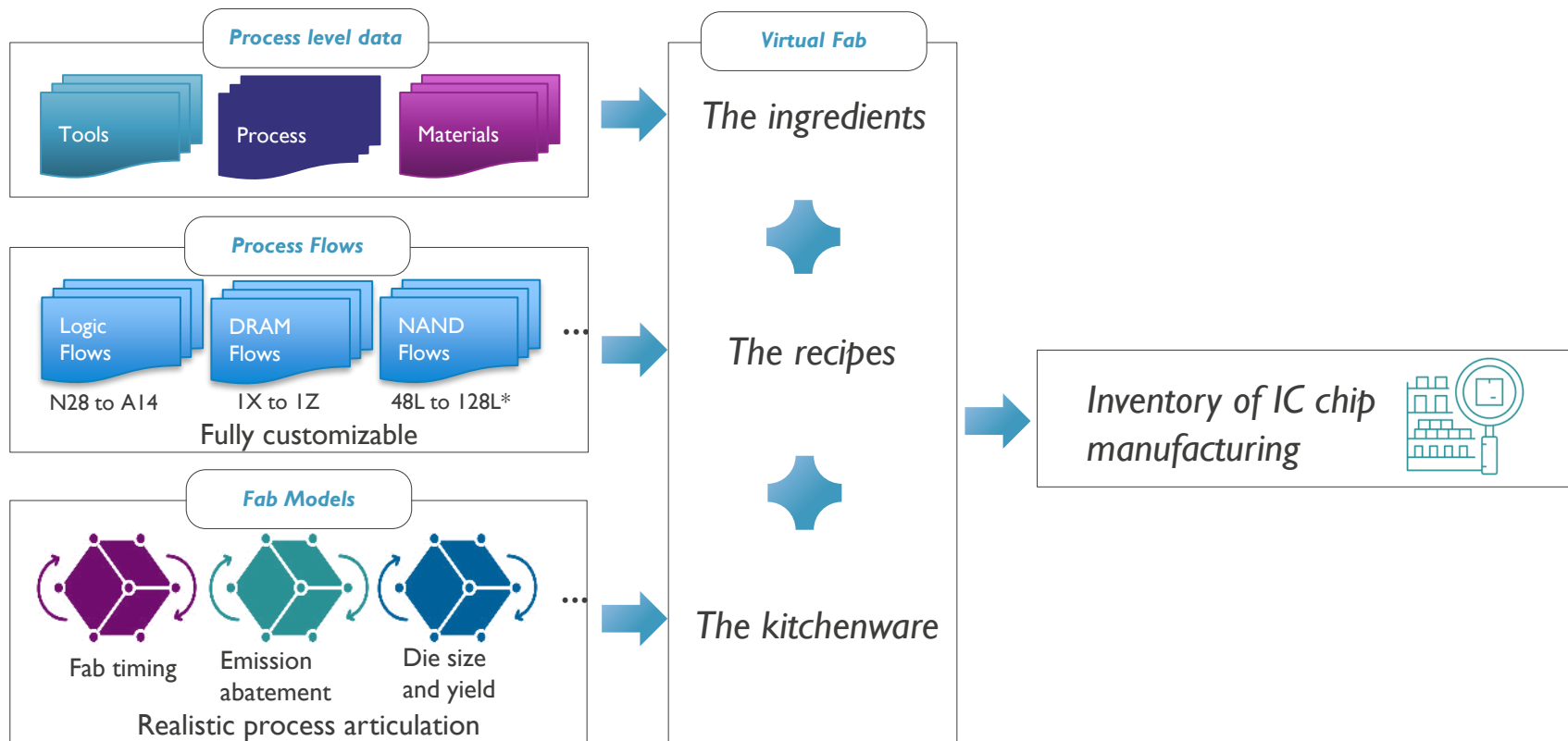
Expand the analysis to:

- Identify **high impact** problems to focus Improve efforts
- Project the **future impact of IC chip manufacturing**



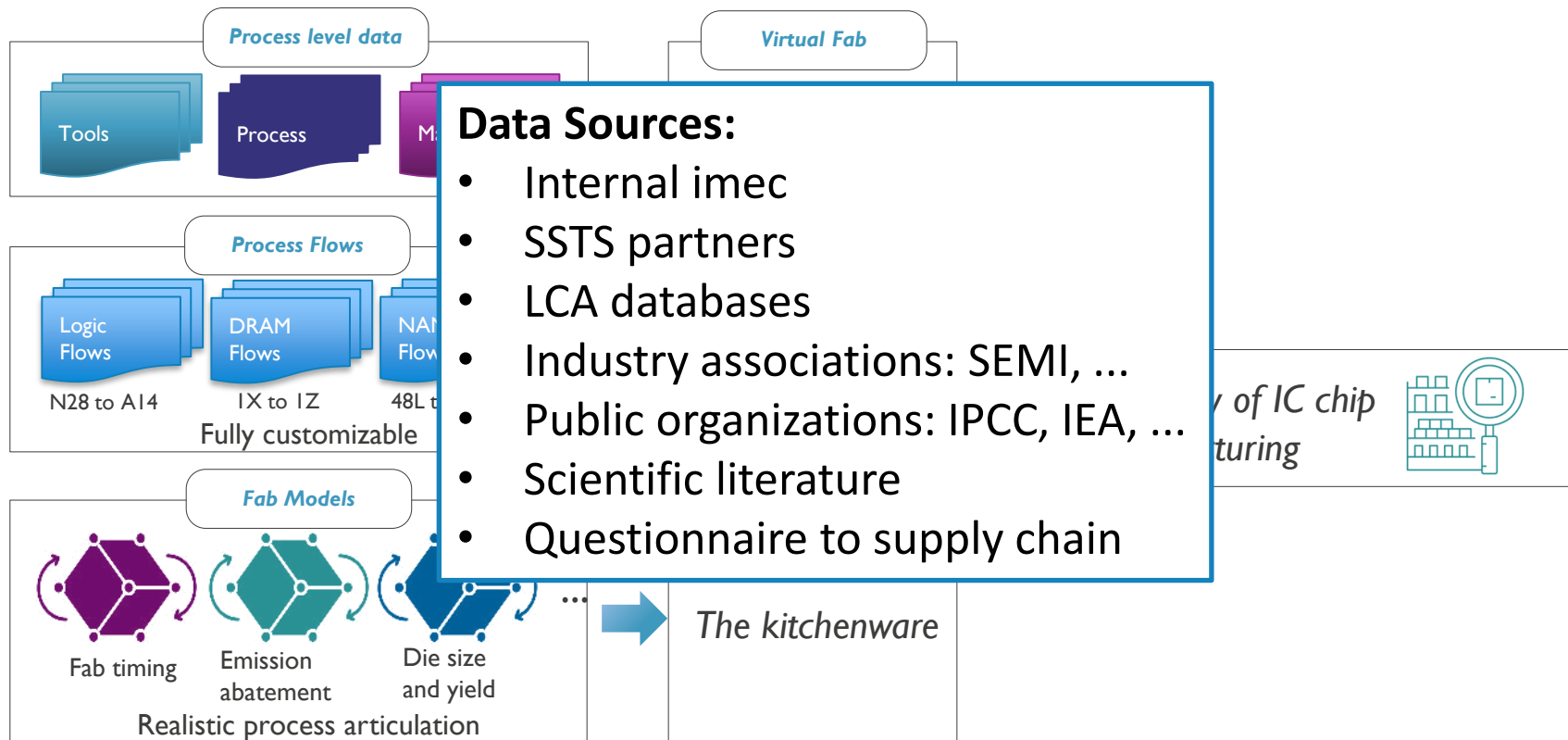
SSTS Assess - Virtual Fab Model

Quantify the footprint of a chip



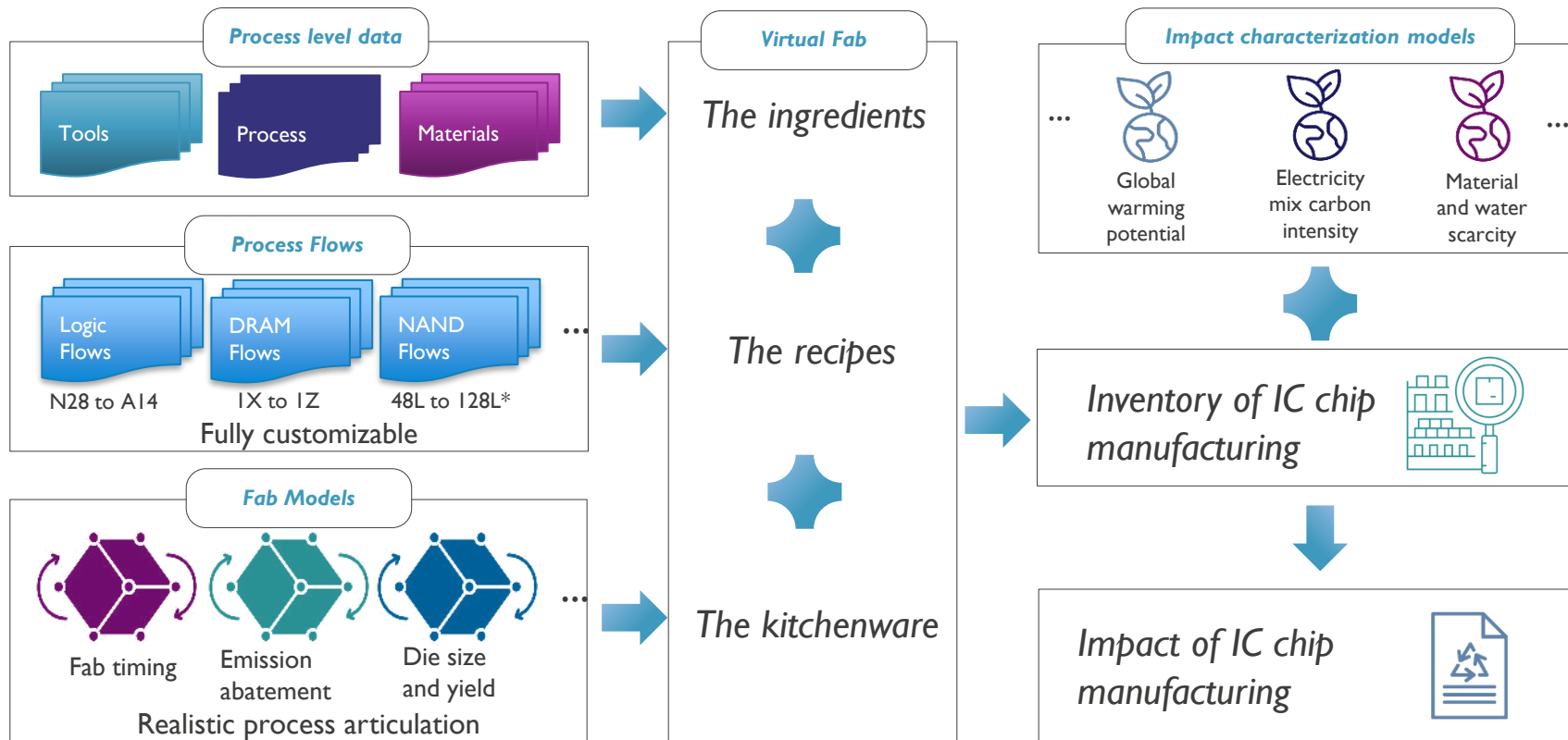
SSTS Assess - Virtual Fab Model

Quantify the footprint of a chip



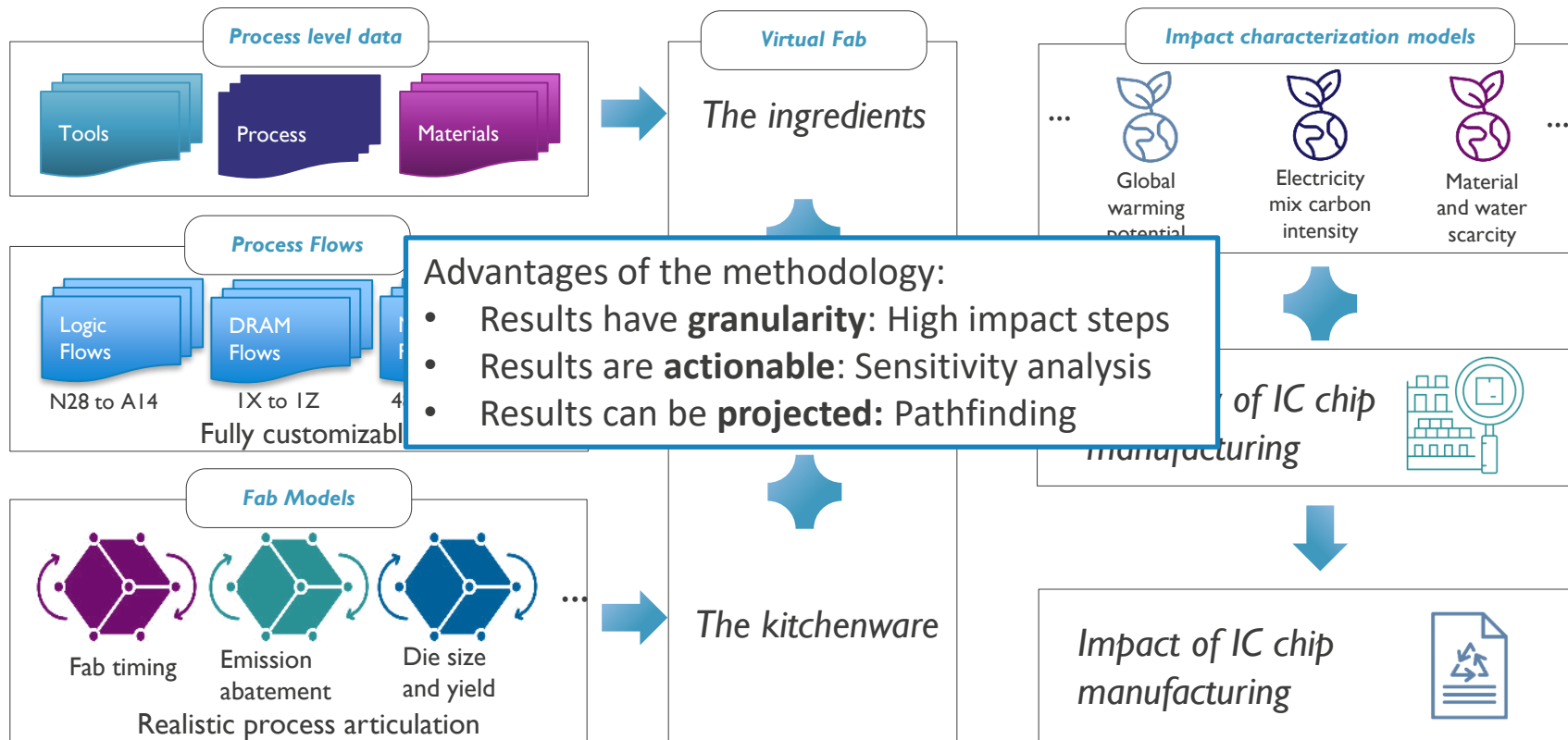
SSTS Assess - Virtual Fab Model

Quantify the footprint of a chip



SSTS Assess - Virtual Fab Model

Quantify the footprint of a chip



Bottom-up vs top-down approach in LCA



Top-down

Benefits:

- Representative of real fabs

Drawbacks:

- Scope 1 depends on declaration protocol
- Scope 3 estimates very difficult
- Highly aggregated data



Complementarity
through benchmarking



Bottom-up

Benefits:

- Results are Granular, Actionable and Projectable

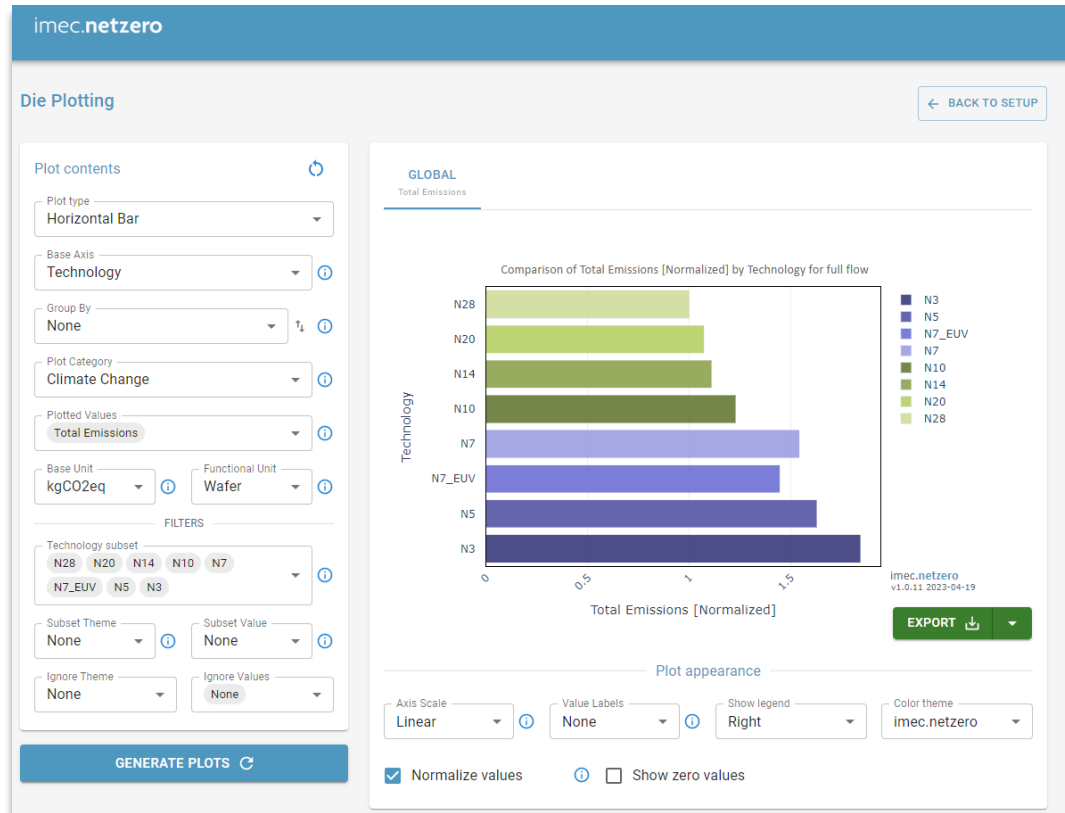
Drawbacks:

- Accounting never 100% complete
- Highly specialized expertise required



imec.netzero Web Application

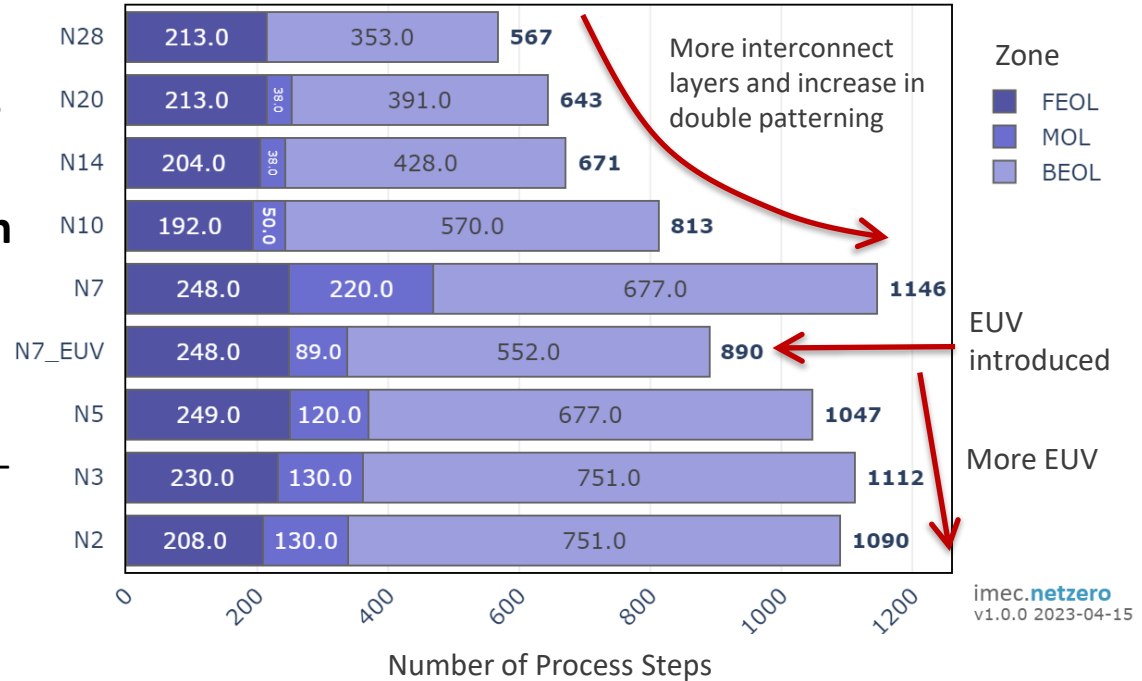
Public version release: June 30th 2023



Complexity Increase of a Mobile SoC

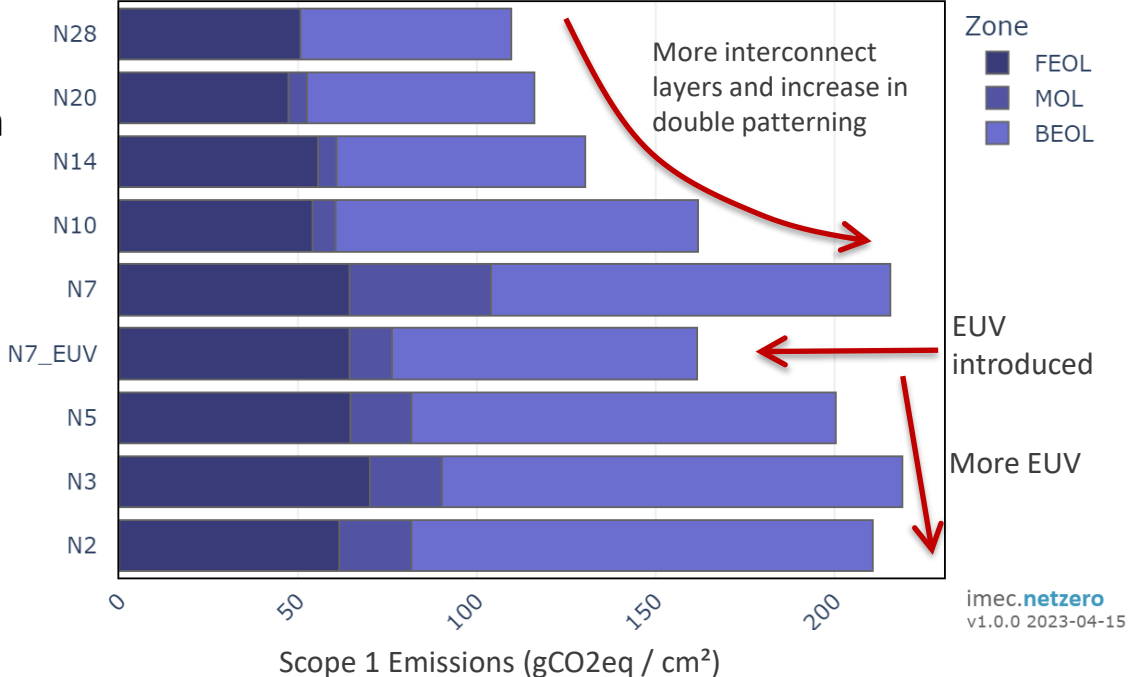
Number of process step evolution per node

- Increase in Complexity node to node where BEOL interconnects dominate
- Introduction of **EUV slows down the increase in complexity:**
 - Less multi-patterning DUV immersion steps
 - Less deposition, Dry-Etch, Wet-Clean, Metrology steps



Direct Emissions (Scope 1)

- Process gases are potent Greenhouse gases => **Deposition and Etch** contribute strongly to direct emissions
- Multi patterning use many repeats of deposition and etch
 ⇔ **By reducing complexity, EUV keeps direct emissions under check**



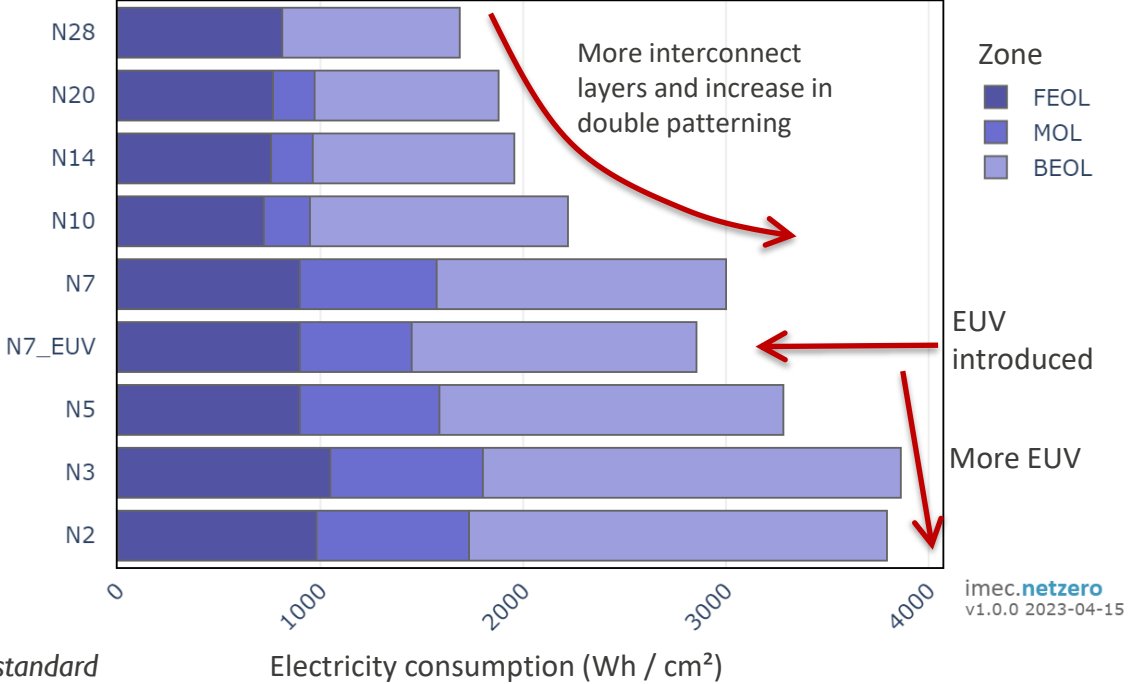
- 10x10mm² die, Murphy yield with 0,15 defect/cm²
- Tier 2C Abatement model (2019 Refinement to the 2006 IPCC Guidelines for National Greenhouse Gas Inventories)
- GHG global warming potential from IPCC AR6

Electricity consumption

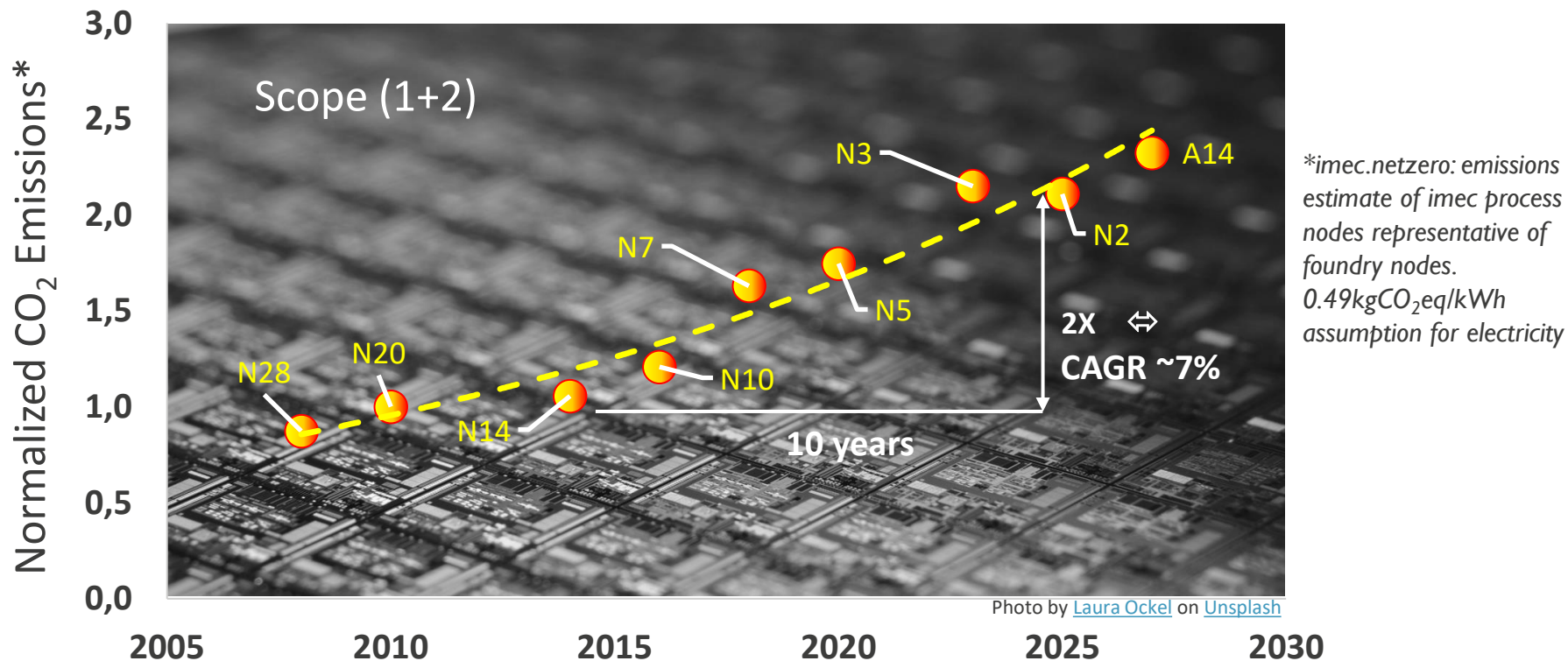
- Increase in process complexity directly leads to **increased electricity consumption**
- Introduction of EUV leads to:
 - **Reduce in process complexity**
 - **Increased electricity consumption** of the litho process area

These two effect counteract each other leading to a continued increase.

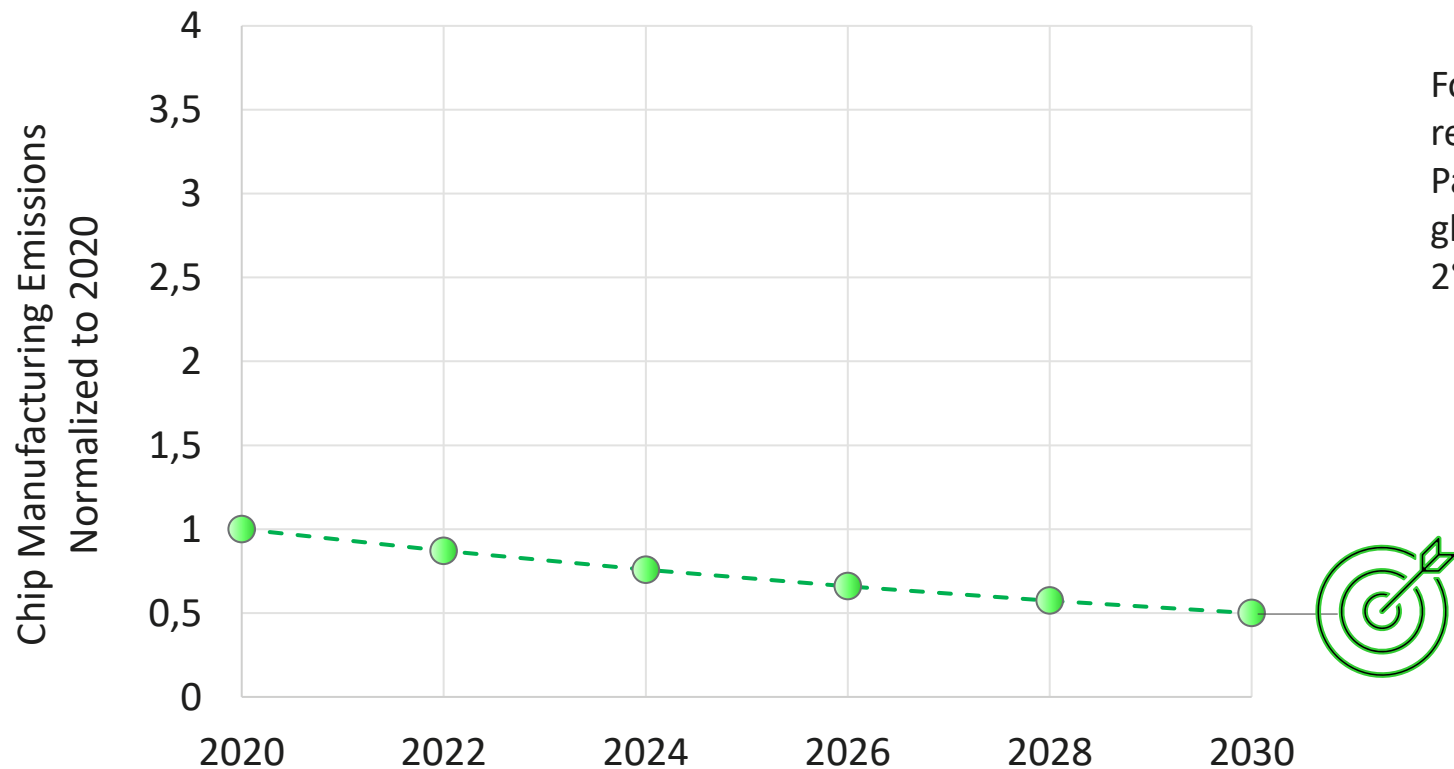
- *10x10mm² die, Murphy yield with 0,15 defect/cm²*
- *Utility electricity consumption modelled using SEMI S23 standard*
- *Tool Utilization assumed using SEMI S23 standard*



Carbon Emissions for Semiconductor Manufacturing are Increasing

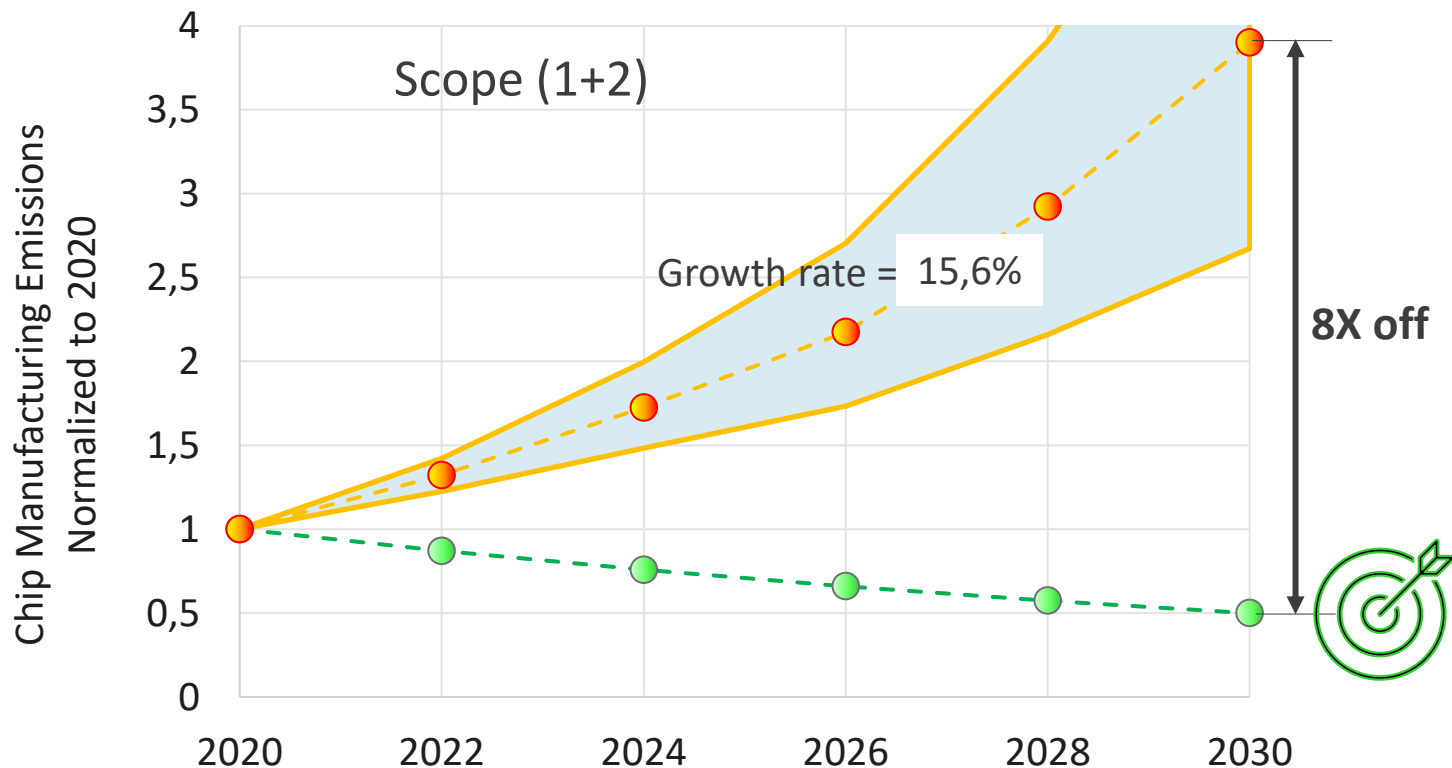


Ideal climate impact scenario for Semiconductor Manufacturing



Following the path recommended by the Paris Agreement to keep global warming under 2°C

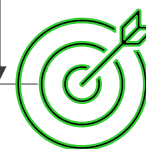
“Do Nothing” Scenario for Semiconductor Manufacturing



Projection includes:

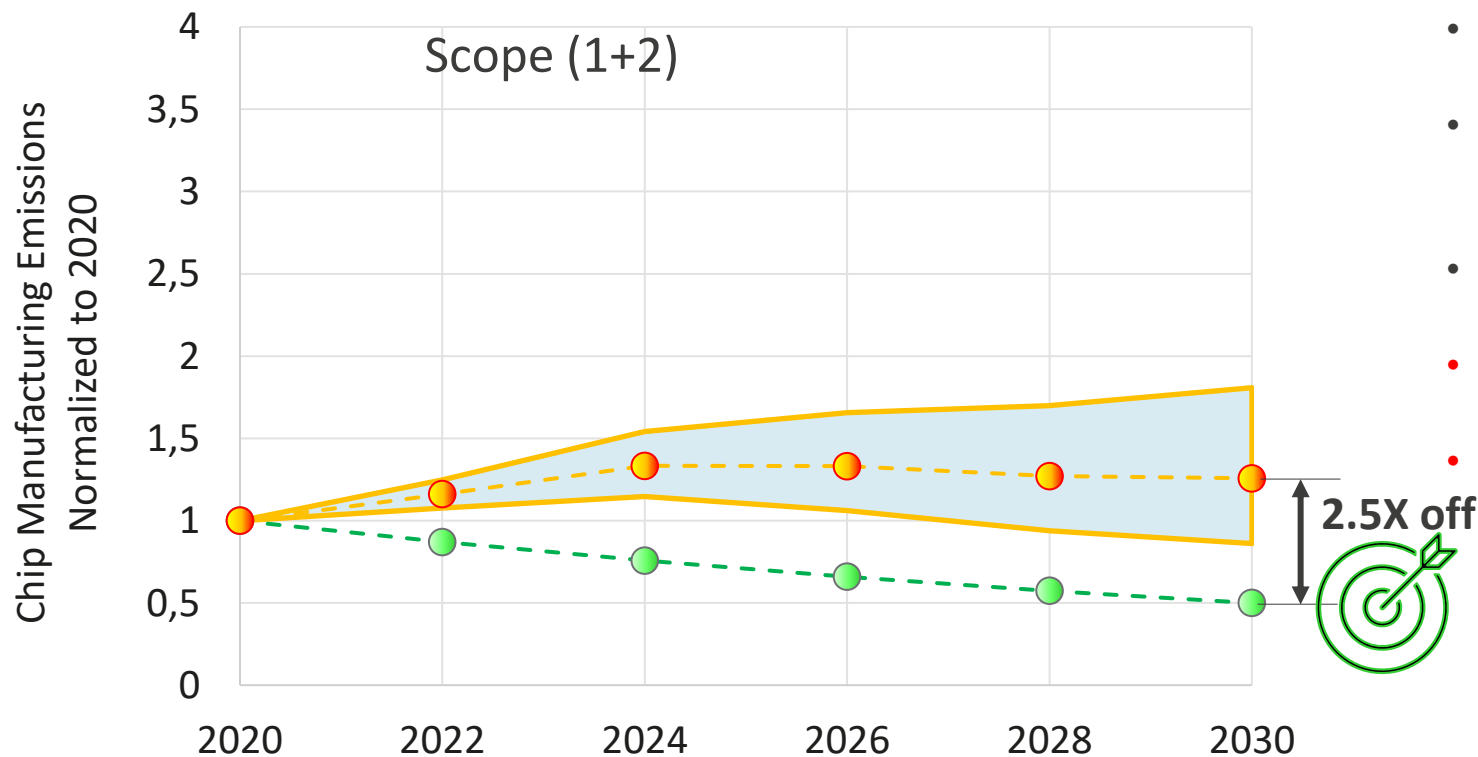
- Evolution of technology mix
- Increase in technology complexity with CAGR ~7%
- ICT Market growth with CAGR 8% ± 4%

Electricity mix and abatement not evolving.



Constant electricity mix (0.49 kCO₂eq/kWh), Tier 2C Abatement (2019 Refinement to the 2006 IPCC Guidelines for National Greenhouse Gas Inventories) and GHG global warming potential (IPCC AR6). Volume technology mix from IBS “Foundry Market Trends and Strategic Implications” Vol 30, N 12, Dec 2021. Logic nodes only.

With Renewable Energy and State-of-the-Art GHG Abatement



Projection includes:

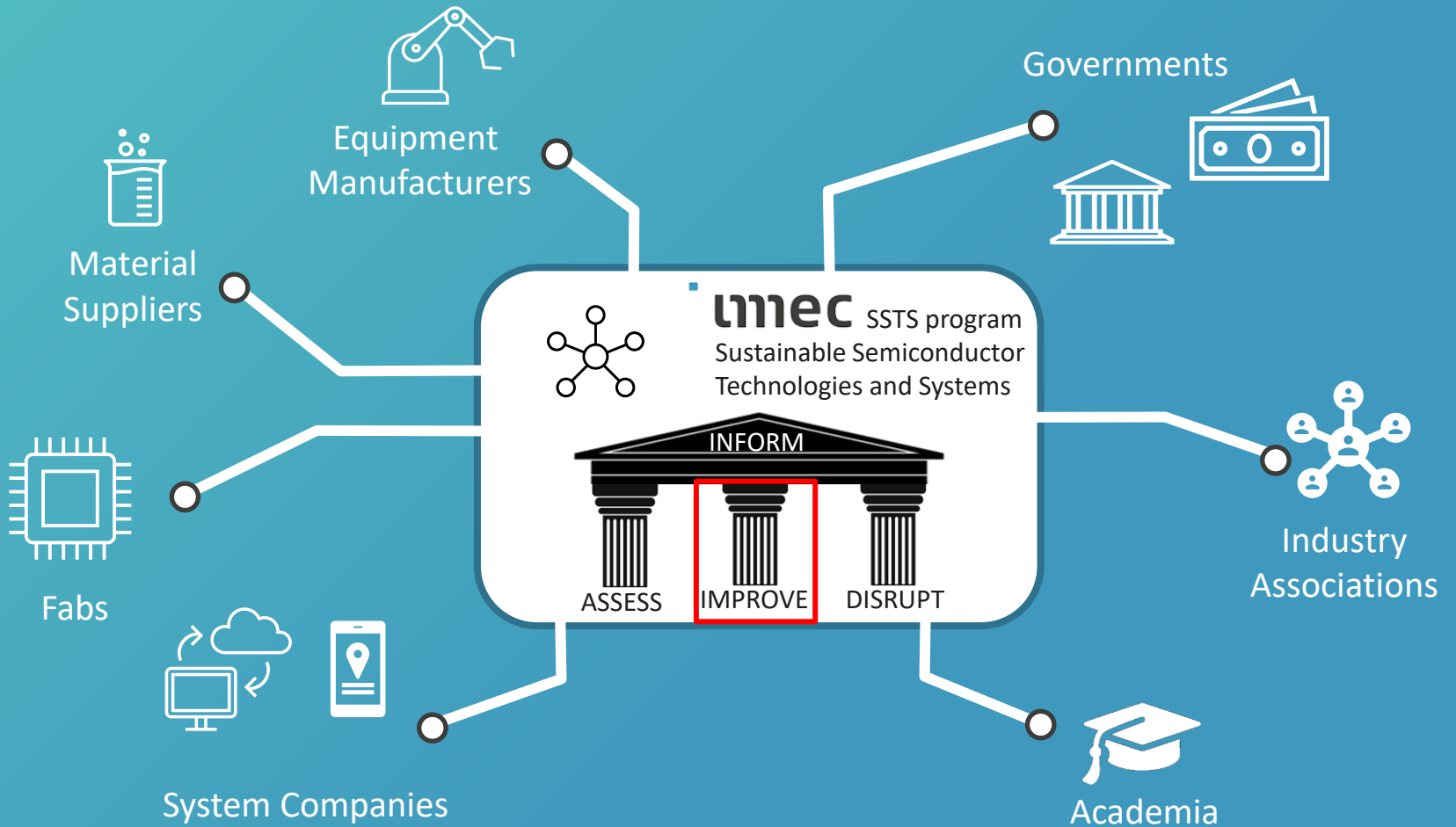
- Evolution of technology mix
- Increase in technology complexity with CAGR ~7%
- ICT Market growth with CAGR 8% ± 4%
- Renewable energy deployment
- State-of-the-art abatement



2.5X off

from 2026 onwards

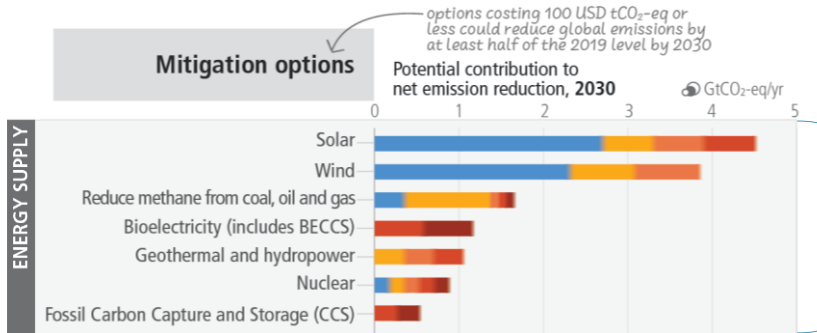
Adding to previous slide: Renewable Energy deployment according to IEA and abatement according to IPCC assumed for the years 2020-2024, State-of-the art Abatement from 2026.



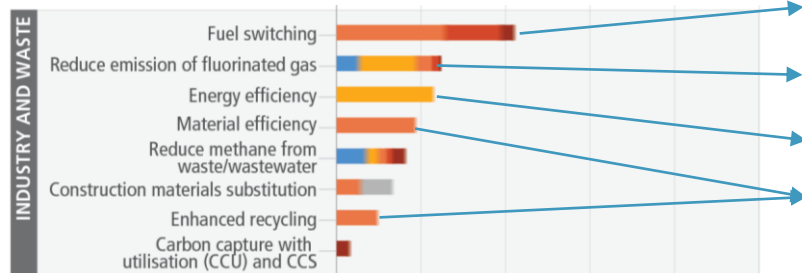
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More renewable electricity !!!



Reduce natural gas consumption

Replace / Reduce / Abate F-Gasses

Energy efficiency & Industry 4.0

Material circularity

Main levers for change
=
IMPROVE Projects

Net lifetime cost of options:

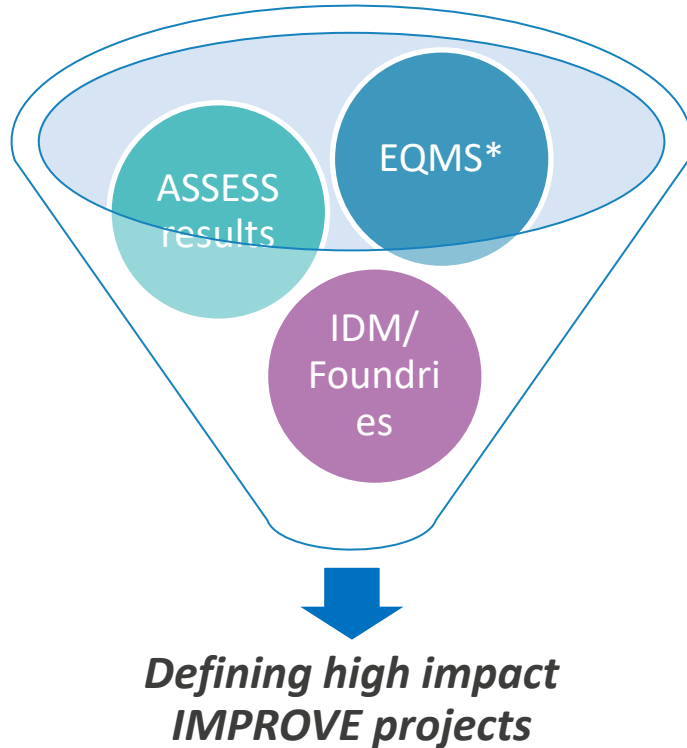


Changes take time.

Need to accelerate on R&D of more sustainable solutions and their implementation in Fabs.

SSTS – *Improve* projects

Focusing on **high-impact**



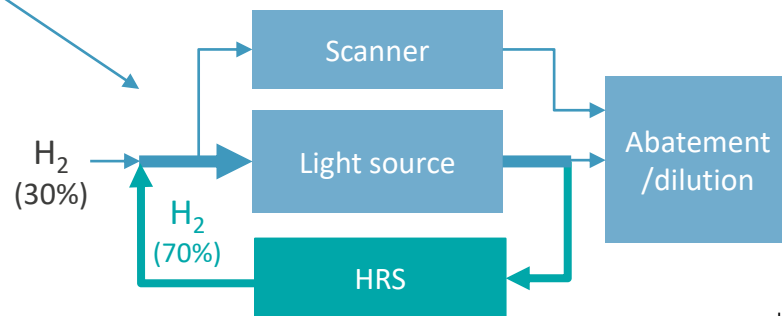
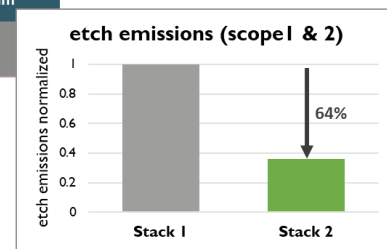
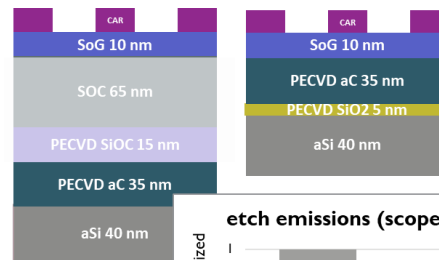
- imec.**netzero** & ASSESS pillar offer in depth analysis for high impact problems.
Key topics for major improvements:
 - **Energy Efficiency**
 - **GHG emission reduction**
- SSTS & partners indicate also work needed in various supplies to the fab, in particular:
 - **Water Management**
 - **Material Circularity**

Without compromising continuous improvement of device performance.

SSTS – Selection of *Improve* projects



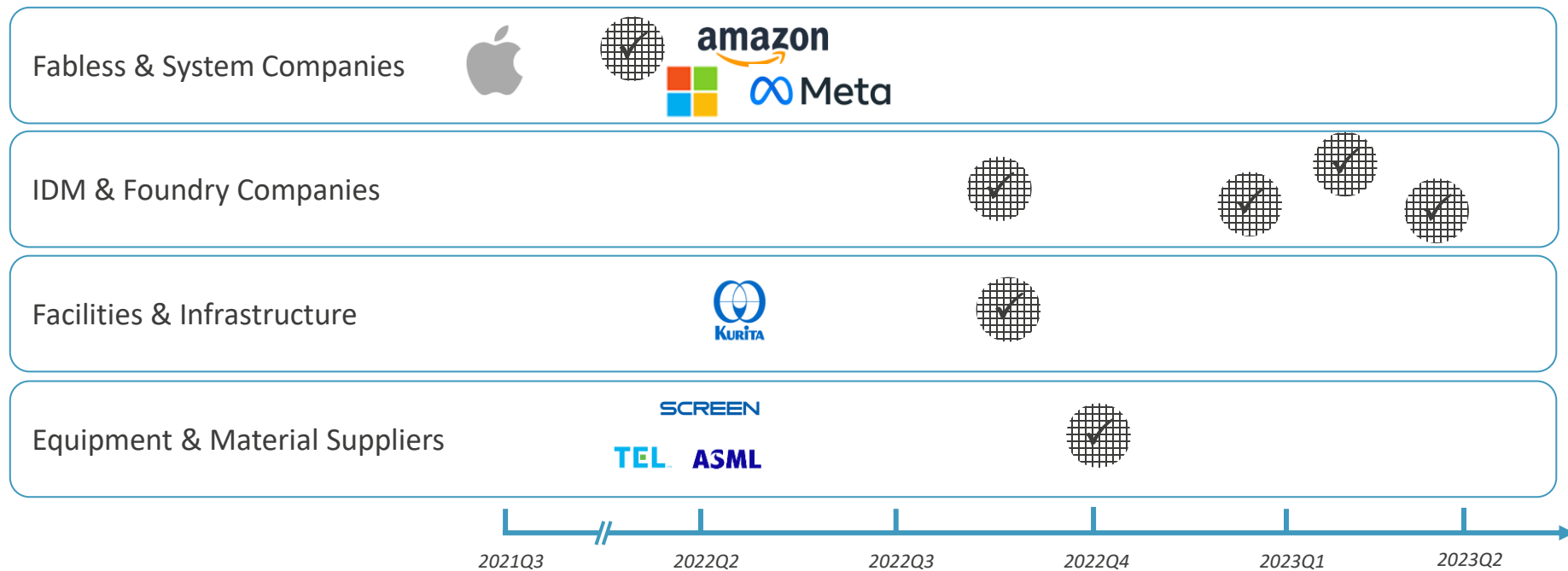
Topic	Scope
Sustainable wet strip solution	Resource efficiency
GHG monitoring	GHG emission
Ge Recovery at epi tool	Material circularity
Reduction of emission with etch optimization	GHG emission
H2 recovery for EUV Scanner	Material circularity
Power consumption reduction for baking steps	Energy saving
Dose reduction on litho resist patterning	Energy saving



Conclusion

Imec building a strong program ecosystem for sustainability

SSTS partnerships



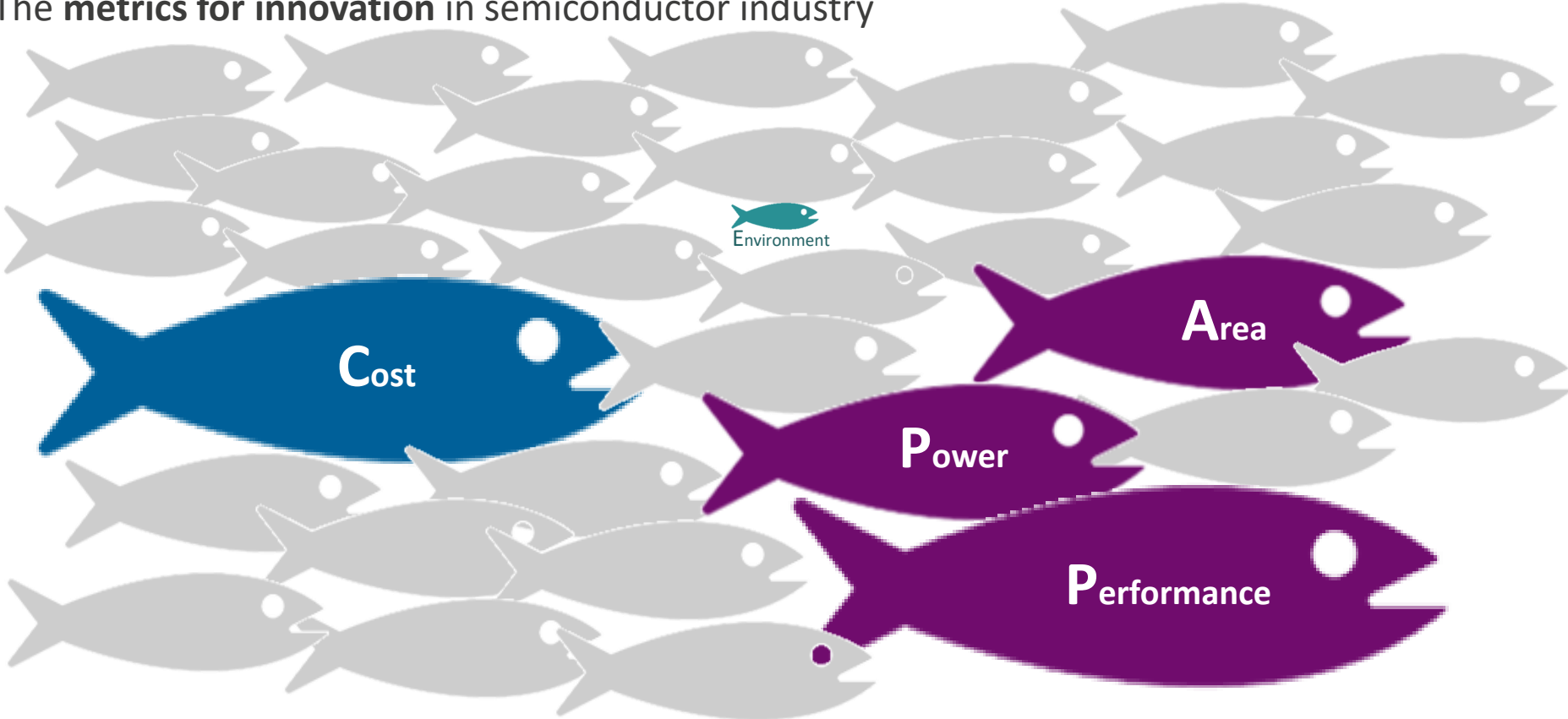
ICOS project: An opportunity to promote sustainability

- Drive European semiconductor industry towards:
 - More **resilient supply chain**
 - More **robust products**
- Adopt **Life-Cycle Thinking** early in Innovation pipelines
- Drive R&D with **Environmental metrics** included in the scorecard:
Power – Performance – Area – Cost - Environment



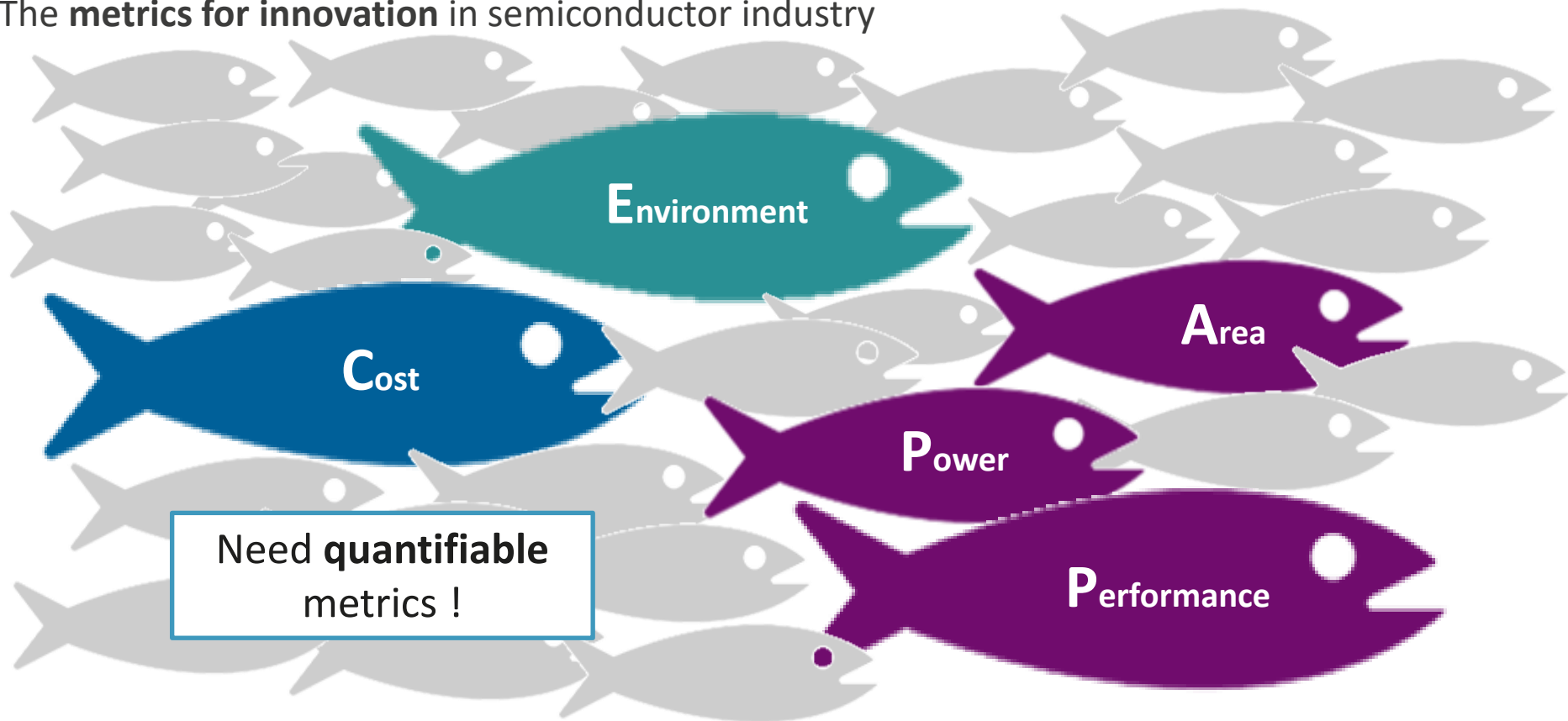
How can innovation drive to more sustainability ?

The **metrics for innovation** in semiconductor industry



How can innovation drive to more sustainability ?

The **metrics for innovation** in semiconductor industry



Need **quantifiable**
metrics !

Acknowledgments

The SSTS team,
our partners and our supporters

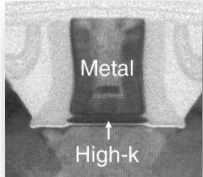
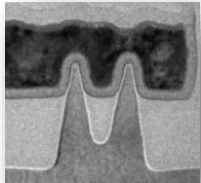










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umec

embracing a better life

Appendix: Studied Logic CMOS technologies and nodes

	← In production →							Future →	
Technology Node	N28	N20	N14	N10	N7	N5	N3	N2	A14
Metal Pitch [nm]	90	64	64	48	40	28	22	21	18
Device structure	 <p>Planar</p>		 <p>FinFETs</p>				 <p>Nanosheets</p>		
Standard cells # tracks	 9T	 9T	 9T	 7.5T	 6.5T	 6T	 6T	 5T	 5T
Scaling boosters					Self Aligned Gate Contact		Metal Gate Cut	Backside power delivery	
Lithography	Immersion (ArFi)							EUV	

Nodes based on imec process flow are generic but representative of foundry nodes.